



## **FOR IMMEDIATE RELEASE**

Nidec Corporation

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Released on February 9, 2017, in Kyoto, Japan

### **Patent Infringement Lawsuit Filed by Our Subsidiary in China**

Nidec Seimitsu Corporation, one of our subsidiaries, filed a patent infringement lawsuit in China. Information on this release is available separately.



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Released on February 9, 2017, in Nagano, Japan

### Patent Infringement Lawsuit Regarding Vibration Motor for Mobile Phone in China

Nidec Seimitsu Corporation (the "Company") today announced the institution of a lawsuit against Shanghai AWA Electronic Equipment Joint Stock Company ("Shanghai AWA") and Sichuan Awa Precision Electric Electrical Appliance Co., Ltd. "Sichuan AWA") at Shanghai Intellectual Property Court for infringement of the Company's Chinese Patent ZL200810133636.8 relating to mobile phone vibration motor technology.

<The Company's intention regarding the lawsuit>

In this lawsuit, the Company seeks injunctive relief to legally stop the sale of patent-infringing products by Shanghai AWA and the manufacturing of patent-infringing products by Sichuan AWA.

Models of patent-infringing products

GS-3209

GS-3200

GS-320H

GD-2335



<Background information (regarding lawsuits)>

September 2015: The Company and Nidec Corporation (collectively, the "Companies") submitted a letter of warning to Shanghai AWA to stop its infringement of the Companies' multiple patent rights.

November 2015: The Company instituted an infringement lawsuit regarding Chinese Patent ZL200910003612.5.

December 2015: Nidec Corporation instituted an infringement lawsuit regarding Chinese Patent ZL01103328.2.

November 2016: Nidec Corporation instituted an infringement lawsuit regarding Chinese Patent ZL02118511.5.

December 2016: The Company instituted an infringement lawsuit regarding Chinese Patent ZL200810133636.8.

(All of the infringement lawsuits were instituted at Shanghai Intellectual Property Court.)

<Background information (regarding invalidation trials)>

January 2016: An invalidation trial (\*A) was instituted against the Company's Chinese Patent ZL200910003612.5.

April 2016: An invalidation trial was instituted against Chinese Patent ZL01103328.2 held by Nidec Corporation.

May 2015: The invalidation trial (\*A) against the Company's Chinese Patent ZL200910003612.5 was withdrawn and, at the same time, a new invalidation trial (\*B) against the same patent was instituted.

September 2016: Regarding the Company's Chinese Patent ZL01103328.2, a trial judgment affirming the validness of the patent right in its entirety has been delivered by Patent Reexamination Board of Patent Office of the People's Republic of China.

November 2016: The invalidation trial (\*B) against the Company's Chinese Patent ZL200910003612.5 was withdrawn and, at the same time, a new invalidation trial (\*C) against the same patent was instituted.

(All of the invalidation trials were instituted at Patent Reexamination Board of Patent Office of the People's Republic of China.)

Having convinced that solving these aforementioned cases by negotiation would not be a practical option, the Company inevitably determined to bring an additional lawsuit against Shanghai AWA and Sichuan AWA at the court to protect the Company's intellectual properties against infringement.

<The mobile phone vibration motor technology owned by the Company>

A mobile phone vibration motor is a compact brush motor equipped with an eccentric weight and installed inside a mobile phone, etc. The motor vibrates as it rotates, informing a mobile phone user of an incoming call without the use of a ringtone.

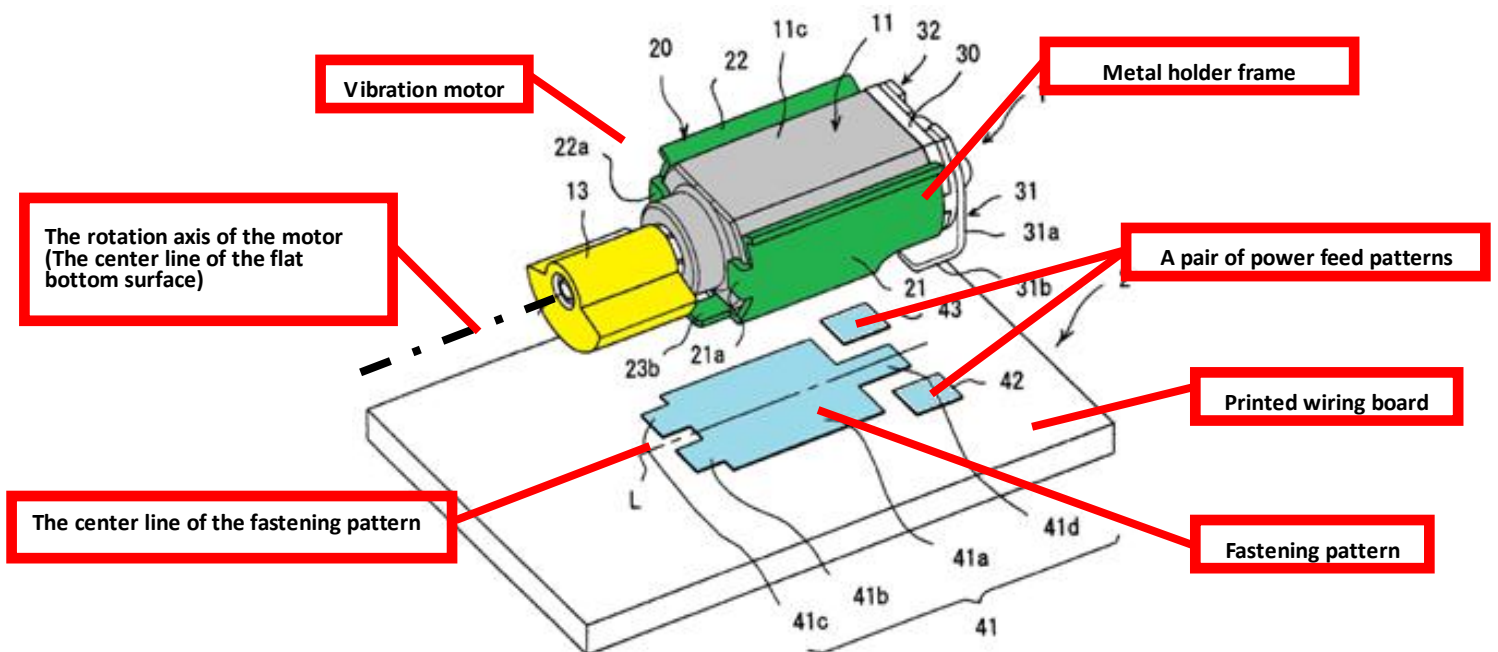


<Explanation of technology of Chinese Patent ZL200810133636.8 of the new lawsuit filed recently>

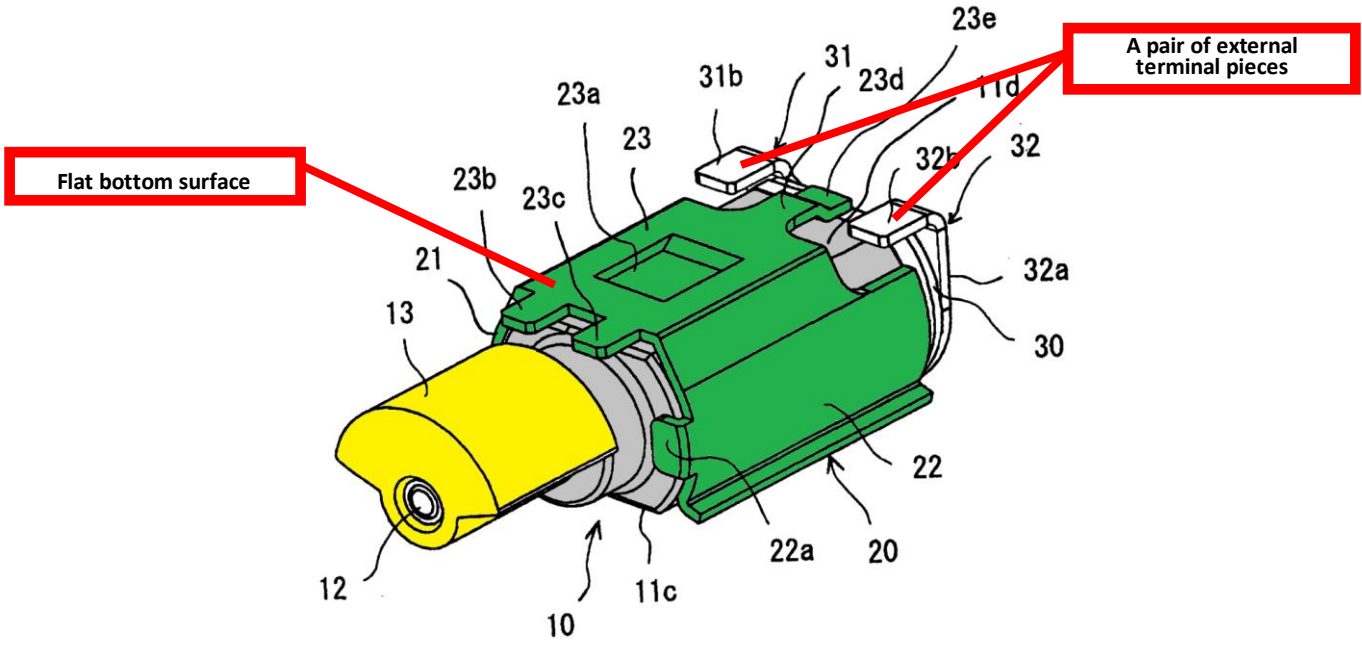
Chinese Patent ZL200810133636.8 (the "Patent") relates to an invention of the surface mounting of a vibration mouter onto a printed wiring board by means of reflow soldering.

A well-known method for the surface mounting of electronic parts such as a resistor and a capacitor is as follows. Solder that is in the form of paste or cream is applied or printed onto a necessary area on a printed wiring board. Next, an electronic part is mounted at a predetermined position on the printed wiring board by a chip mouter. Finally, the mounted electronic part, together with the printed wiring board, undergoes a solder-melting process by going through a high-temperature electric furnace. The electronic part is solder-bonded to the printed wiring board in this way. The vibration motor of the Patent is also mounted in the same way as above. However, when a vibration motor is mounted at a predetermined position on a printed wiring board by a chip mouter, the following problem occurs. A certain level of deviation inevitably occurs in the process of the positioning of the flat bottom surface of a metal holder frame, a fastening pattern, a pair of external terminal pieces, and a pair of power feed patterns in relation to one another. As a result of going through the processes of solder melting at an electric furnace and subsequent cooling for fixation, in some cases, the rotation axis of a motor (i.e., the center line of the flat bottom surface) is not in alignment with the center line of the fastening pattern. In prior art, the lack of alignment results in a decrease in yield.

In view of the above problem, the Patent provides a board mount structure of a vibration motor that makes it possible to, by utilizing self alignment, bring the center line of a flat bottom surface into alignment with the center line of a fastening pattern even when a certain level of deviation occurs in the process of the positioning of the flat bottom surface of a metal holder frame and the fastening pattern.



Perspective view of the state of the mounting of a vibration motor onto a printed wiring board



Back perspective view of the vibration motor



<Intellectual Property Rights>

The lists below show a portfolio of intellectual property rights held by the Company regarding the motor cover of a vibration motor for a mobile phone and regarding an eccentric weight.

Portfolio of patent rights and other IP rights held by Nidec Seimitsu Corporation

JP Patent 3172487	CN Patent ZL200410083318.7
JP Patent 3902618	CN Patent ZL200510054879.9
JP Patent 4104636	CN Patent ZL200810133636.8 New lawsuit filed recently
JP Patent 4159441	CN Patent ZL200810149708.8
JP Patent 4183739	CN Patent ZL200910003612.5 Lawsuit filed previously
JP Patent 4601648	CN Utility Model ZL201420194272.5
JP Patent 4887064	CN Utility Model ZL201420211454.9
JP Patent 5060197	CN Utility Model ZL201420620572.5
JP Patent 5060228	CN Utility Model ZL201520503822.1
JP Patent 5074935	CN Utility Model ZL201620397503.1
JP Patent 5923794	CN Design ZL201030601873.0
JP Design 1202942	CN Design ZL201230137110.4
JP Design 1202943	CN Design ZL201430096336.3
JP Design 1217933	US Patent 6081055
JP Design 1217964	US Patent 7023114
JP Design 1303191	US Patent 7045921
JP Design 1303194	US Patent 7567002
JP Design 1343868	US Patent 7679240
JP Design 1343870	US Patent 7888832
JP Design 1405196	US Design D603795
JP Design 1450728	KR Design 30-0482473



Portfolio of patent rights and other IP rights held by Nidec Corporation (For your information)

JP Patent 3076017	CN Patent ZL01103328.2 <b>Lawsuit filed previously</b>
JP Patent 3205987	CN Patent ZL02118511.5 <b>Lawsuit filed previously</b>
JP Patent 3362725	CN Patent ZL99110047.6
JP Patent 3528787	US Patent 6608413
JP Patent 3570391	TW Patent 145066
JP Patent 3573121	TW Patent 159215
JP Patent 3601490	TW Patent 190751
JP Patent 3614093	KR Patent 358462
JP Patent 4026536	KR Patent 743001
JP Design 1156031	KR Patent 880507
JP Design 1156032	TH Patent 25863
JP Design 1156264	ID Patent ID0015070
JP Design 1156265	VN Patent 4466
JP Design 1156266	FI Patent 116644
JP Design 1156267	SE Patent 519637
JP Design 1156268	
JP Design 1156269	
JP Design 1156270	
JP Design 1156271	